

10-20-2000

RNEY DOCKET NO: AB-933 US

RE

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

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TO THE HONORABLE DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE. PLEASE RECORD THE ATTACHED ORIGINAL DOCUMENTS OR COPY THEREOF.

1. Name of conveying party(ies):

- (a) Chan Seung Hwang,
(b) Seung Ouk Jung
(c)

Additional name(s) of conveying party(ies) attached?

☐ Yes☒ No

2. Name and address of receiving party(ies):

Name: **Samsung Electronics Co., Ltd.**Street Address: **416, Maetan-dong Paldal-ku, Suwon -city**
Kyungki-do, Republic of Korea

09/672379

3. Nature of Conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: **March 10, 2000**

Name and address of receiving party(ies):

Name:

Street Address:

City:

{State}

{Zip}

Country:

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: **March 10, 2000**

A. Patent Application No.(s) -

Title: **Chip Size Package Having Concave Pattern In Bump Pad Area Of Redistribution Patterns And Method for Manufacturing The Same**

B. Patent No.(s)

Additional numbers attached?



Yes



No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **David W. Heid, Esq.**Internal Address: **SKJERVEN MORRILL MacPHERSON LLP**Street Address: **25 METRO DRIVE, SUITE 700**City **SAN JOSE** State **CA** Zip **95110**6. Total number of applications and patents involved: **1**7. Total fee (37 CFR 3.41): **\$40.00**

Authorized to be charged to Deposit Account 19-2386



Charge Deposit Account 19-2386 for any additional fees required for this conveyance and credit deposit account 19-2386 any amounts overpaid

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8. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*David W. Heid
Name of Person Signing

Signature

Date

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ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Chan Seung HWANG of No. 1309-1201, Dongbaek Woosung Apt.
Sanbon-2-dong, Koonpo-city
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Seung Ouk JUNG of No. 542-2, Bupyung-1-dong
Bupyung-ku, Incheon-city
Kyungki-do, Republic of Korea

hereby sell, assign and transfer to Samsung Electronics Co., Ltd., a Korean corporation, having a place of business at 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea, its successors and assigns, the entire right, title and interest throughout the world in our invention in

Chip Size Package Having Concave Pattern In Bump Pad Area Of Redistribution Patterns
And Method For Manufacturing The Same

for which we have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 10th day of March 10, 2000.

Chan Seung Hwang
Chan Seung HWANG

Executed this 10th day of March 10, 2000.

Seung Ouk Jung
Seung Ouk JUNG